

40V P-Channel Trench Power MOSFET

General Description

The CH120P04E uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as -4.5V. This device is suitable for use as a wide variety of applications.

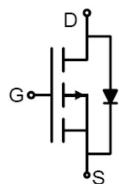
Features

- $V_{DS} = -40V$, $I_D = -107A$
- $R_{DS(ON)} < 5.5m\Omega$ @ $V_{GS} = -10V$
- $R_{DS(ON)} < 7.8m\Omega$ @ $V_{GS} = -4.5V$
- High Power and current handing capability
- Lead free product is acquired

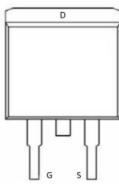
Application

- Load switch
- Power Management
- PWM Applications

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100% ΔV_{ds} TESTED!



Schematic Diagram



Marking and pin Assignment



TO-263 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
CH120P04E	CH120P04E	TO-263			

Table 1. Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0V$)	-40	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0V$)	± 20	V
I_D	Drain Current-Continuous($T_c=25^\circ C$)	-107	A
	Drain Current-Continuous($T_c=100^\circ C$)	-75	A
$I_{DM(pulse)}$	Drain Current-Continuous@ Current-Pulsed (Note 1)	-428	A
P_D	Maximum Power Dissipation($T_c=25^\circ C$)	115	W
	Maximum Power Dissipation($T_c=100^\circ C$)	57	W
E_{AS}	Avalanche energy (Note 2)	576	mJ
T_J , T_{STG}	Operating Junction and Storage Temperature Range	-55 To 175	°C

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
R_{JC}	Thermal Resistance, Junction-to-Case		1.3	°C/W

Table 3. Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=-250\mu\text{A}$	-40			V
Id_{SS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-40\text{V}$, $V_{\text{GS}}=0\text{V}$			-1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$			± 100	nA
$\text{V}_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_{\text{D}}=-250\mu\text{A}$	-1	-1.7	-2.5	V
g_{FS}	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$, $I_{\text{D}}=-20\text{A}$		59		S
$\text{R}_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance	$V_{\text{GS}}=-10\text{V}$, $I_{\text{D}}=-20\text{A}$		4.5	5.5	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-20\text{A}$		6.1	7.8	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{DS}}=-20\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1.0\text{MHz}$		6638		pF
C_{oss}	Output Capacitance			545		pF
C_{rss}	Reverse Transfer Capacitance			345		pF
R_g	Gate resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $f=1.0\text{MHz}$		1.9		Ω
Switching Parameters						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{GS}}=-10\text{V}$, $V_{\text{DS}}=-20\text{V}$, $R_{\text{L}}=1\Omega$, $R_{\text{GEN}}=3\Omega$		16		nS
t_r	Turn-on Rise Time			17		nS
$t_{\text{d(off)}}$	Turn-Off Delay Time			68		nS
t_f	Turn-Off Fall Time			31		nS
Q_g	Total Gate Charge	$V_{\text{GS}}=-10\text{V}$, $V_{\text{DS}}=-20\text{V}$, $I_{\text{D}}=-20\text{A}$		118		nC
Q_{gs}	Gate-Source Charge			13		nC
Q_{gd}	Gate-Drain Charge			22		nC
Source-Drain Diode Characteristics						
I_{SD}	Source-Drain Current (Body Diode)				-99	A
V_{SD}	Forward on Voltage ^(Note 3)	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=-20\text{A}$			-1.2	V
t_{rr}	Reverse Recovery Time	$I_{\text{F}}=-20\text{A}$, $d\text{I}/dt=500\text{A}/\mu\text{s}$		24		ns
Q_{rr}	Reverse Recovery Charge	$I_{\text{F}}=-20\text{A}$, $d\text{I}/dt=500\text{A}/\mu\text{s}$		140		nC

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

Notes 2.E_AS condition: $T_J=25^\circ\text{C}$, $V_{\text{DD}}=15\text{V}$, $V_G=-10\text{V}$, $R_g=25\Omega$, $L=0.5\text{mH}$.

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

Typical Electrical And Thermal Characteristics (Curves)

Figure 1. Output Characteristics

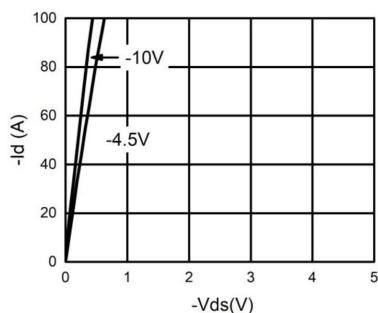


Figure 2. Transfer Characteristics

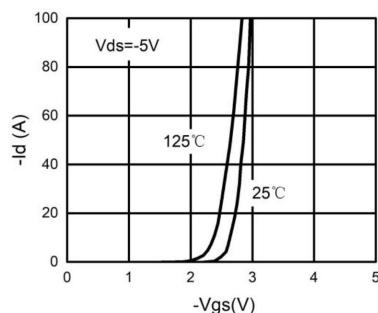


Figure 3. Power Dissipation

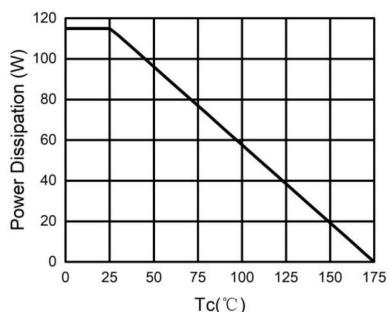


Figure 4. Drain Current

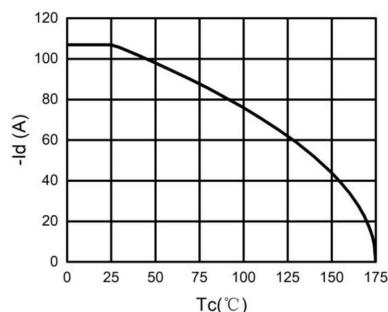


Figure 5. BV_{DSS} vs Junction Temperature

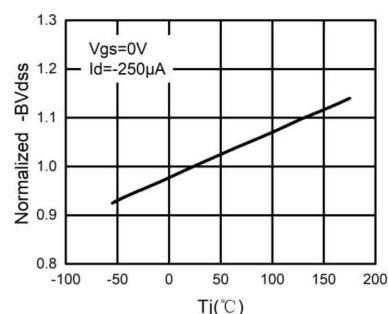


Figure 6. R_{DSON} vs Junction Temperature

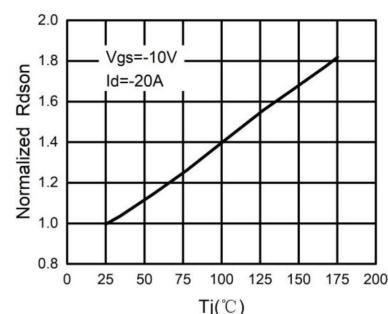
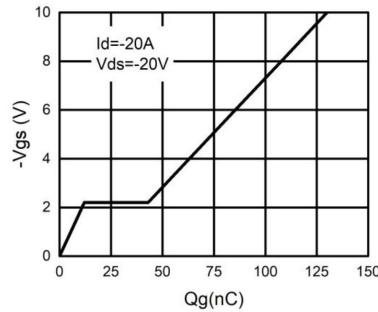
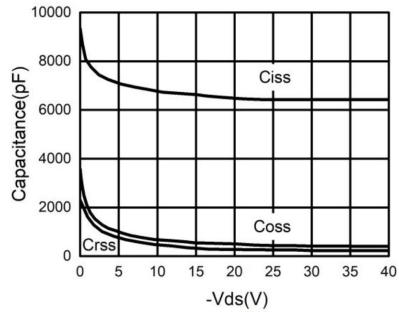
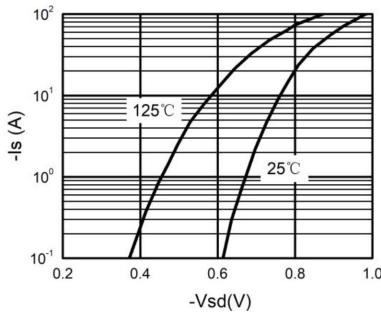
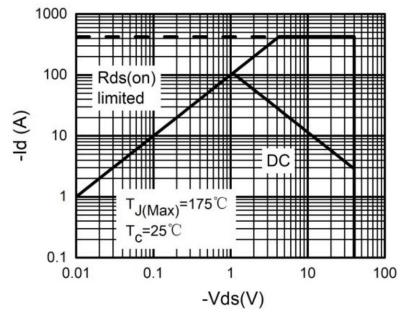
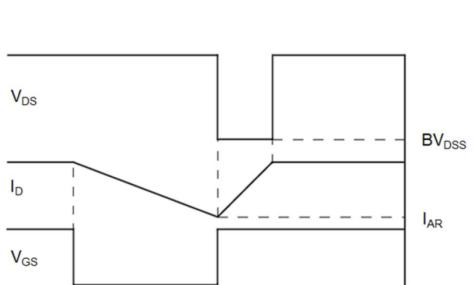
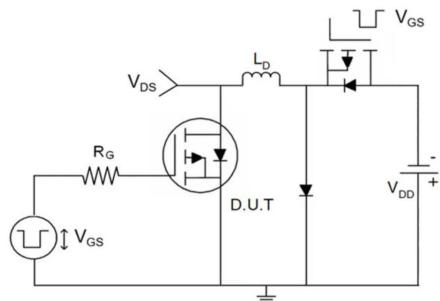


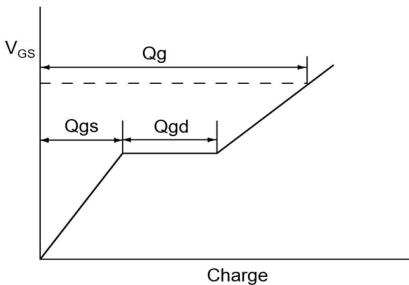
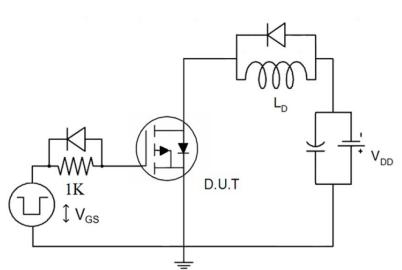
Figure 7. Gate Charge Waveforms**Figure 8. Capacitance****Figure 9. Body-Diode Characteristics****Figure 10. Maximum Safe Operating Area**

Test Circuit

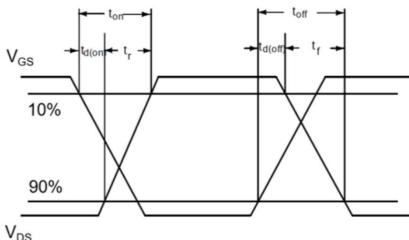
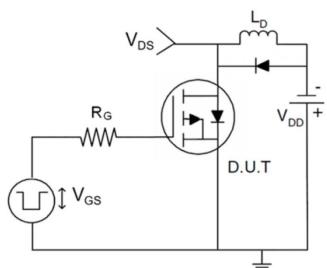
1) E_{AS} Test Circuits

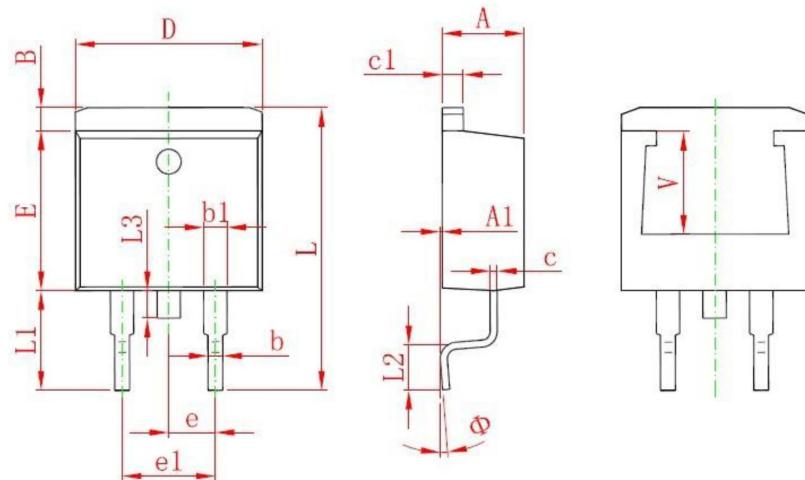


2) Gate Charge Test Circuit



3) Switch Time Test Circuit



TO-263 Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.470	4.670	0.176	0.184
A1	0.000	0.150	0.000	0.006
B	1.120	1.420	0.044	0.056
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.310	0.530	0.012	0.021
c1	1.170	1.370	0.046	0.054
D	10.010	10.310	0.394	0.406
E	8.500	8.900	0.335	0.350
e	2.540 TYP.		0.100TYP.	
e1	4.980	5.180	0.196	0.204
L	14.940	15.500	0.588	0.610
L1	4.950	5.450	0.195	0.215
L2	2.340	2.740	0.092	0.108
L3	1.300	1.700	0.051	0.067
V	5.600 REF.		0.220REF.	
Φ	0°	8°	0°	8°

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